

G00002

ABSTRACT OF THE DISCLOSURE

SEMICONDUCTOR DEVICE

A semiconductor device, comprising: a semiconductor chip (1) having external electrodes (2) on one surface thereof; an insulating base film (4) having a lead pattern (3) on one surface thereof, and inner leads (9) provided on said one surface to be connected to said lead pattern; solder balls (20) arranged on a remaining surface of said insulating base film (4) to be electrically connected to said lead pattern (3); and a cushioning material (50) for relaxing thermal stress between said semiconductor chip (1) and said lead pattern (3); wherein said semiconductor chip (1) is mounted on said insulating base film (4), so that said cushioning material (50) is positioned between said one surface of said semiconductor chip (1) and said one surface of said insulating base film (4), and said external electrodes (2) are electrically connected to said inner leads (9) to provide joined portions (9A), so that said joined portions (9A) are sealed by a mold resin (40).

(Figure 4A)



162162